

PATENT ABSTRACTS OF JAPAN

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(54) SUBSTRATE JOINING DEVICE

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a substrate joining device capable of preventing mispositioning and improving substrate efficiency and production efficiency at the time of joining two sheets of substrates.

SOLUTION: The substrate joining device for joining the first substrate F and the second substrate A by superposing these substrates on each other via a sealant S in the state of maintaining a prescribed spacing therebetween by spacers has a positioning means 76 which relatively positions the first substrate F and the second substrate A, a spacing adjusting means 97 for pressurizing the first substrate F and the second substrate A in a positioned state under prescribed load to bring the spacing between the first substrate F and the sec-

and substrate A closer until the spacing is regulated by spacers, thereby adjusting the spacing to the prescribed spacing and a sealant curing means 130 for joining the first substrate F and the second substrate A by maintaining the spacing adjusted by this spacing adjusting means 97 and curing the sealant S in the state of maintaining the prescribed spacing.

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